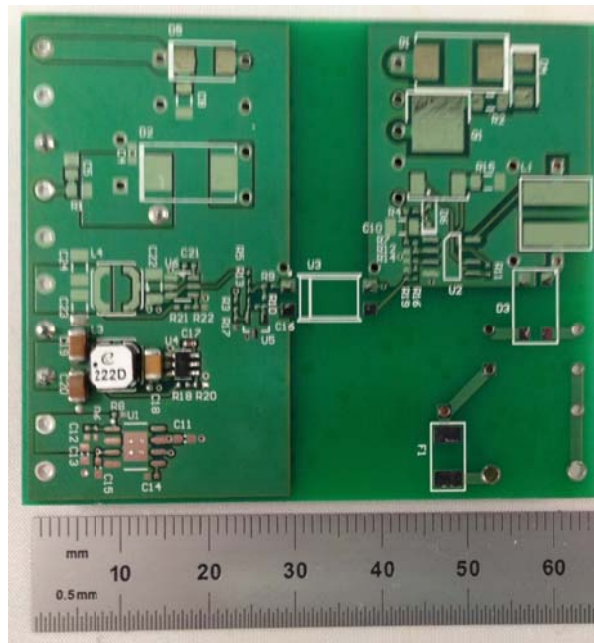
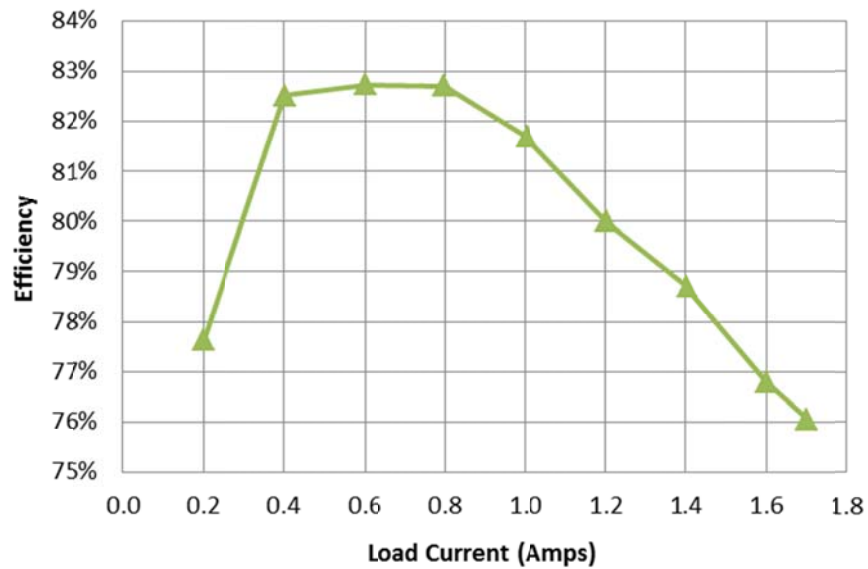


## 1 Photos

The photograph below shows the PMP9726 Rev A prototype assembly. This circuit was built on a PMP9661 Rev A PCB.



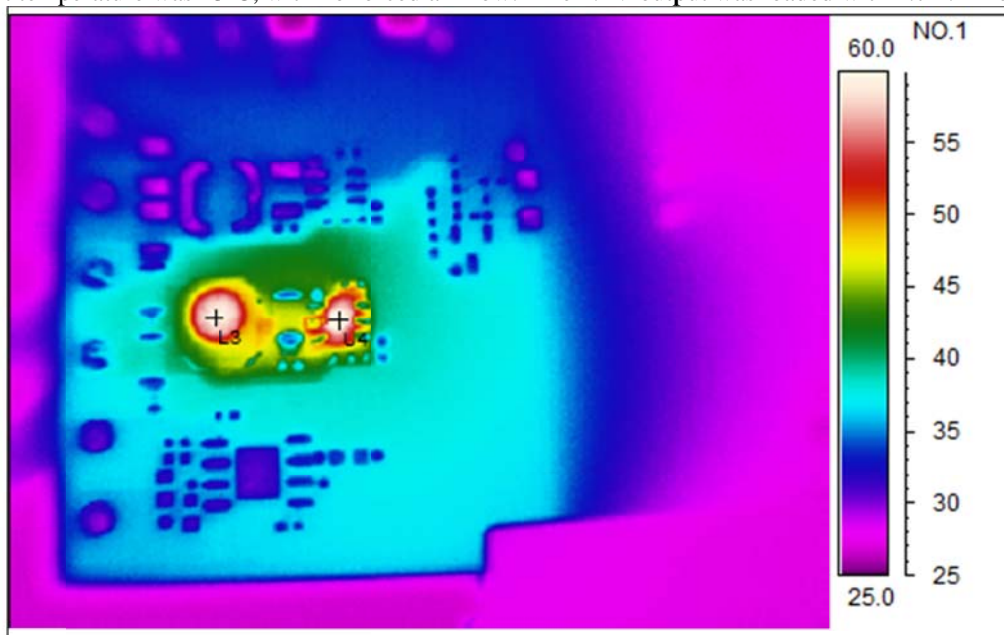
## 2 Efficiency



Iout	Vout	Vin	Iin	Pout	Losses	Efficiency
0.000	1.208	12.03	0.0047	0.00	0.057	0.1%
0.201	1.207	12.02	0.026	0.24	0.070	77.6%
0.403	1.205	12.01	0.049	0.49	0.103	82.5%
0.602	1.204	12.00	0.073	0.72	0.151	82.7%
0.799	1.203	11.98	0.097	0.96	0.201	82.7%
1.004	1.201	12.00	0.123	1.21	0.270	81.7%
1.202	1.200	12.02	0.150	1.44	0.361	80.0%
1.402	1.199	12.00	0.178	1.68	0.455	78.7%
1.600	1.198	12.00	0.208	1.92	0.579	76.8%
1.700	1.198	12.01	0.223	2.04	0.642	76.0%

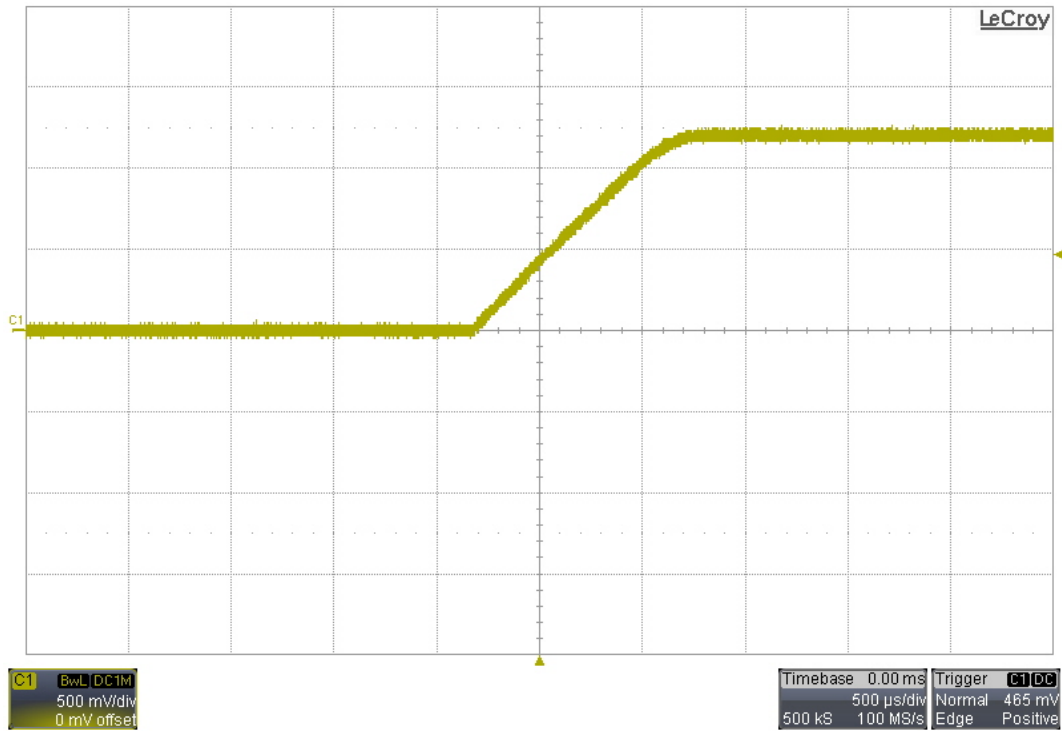
### 3 Thermal Image

The ambient temperature was 25°C, with no forced air flow. The 1.2V output was loaded with 1.7A. The input was 12Vdc.

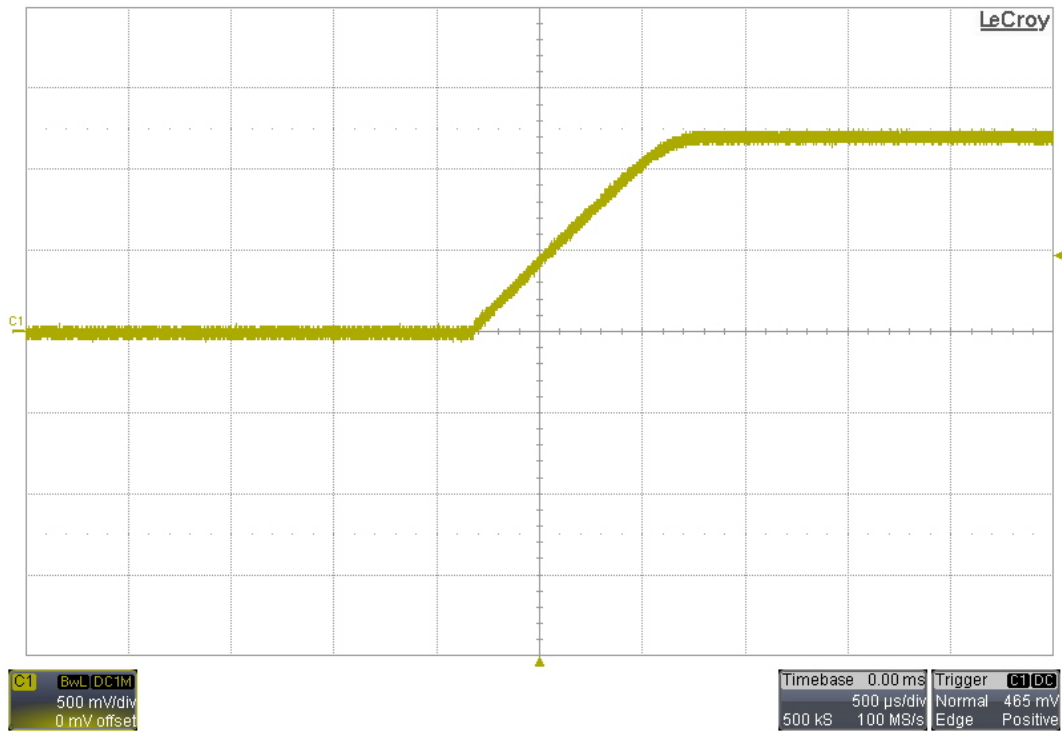


Spot analysis	Value
L3 Temperature	59.4°C
U4 Temperature	60.9°C

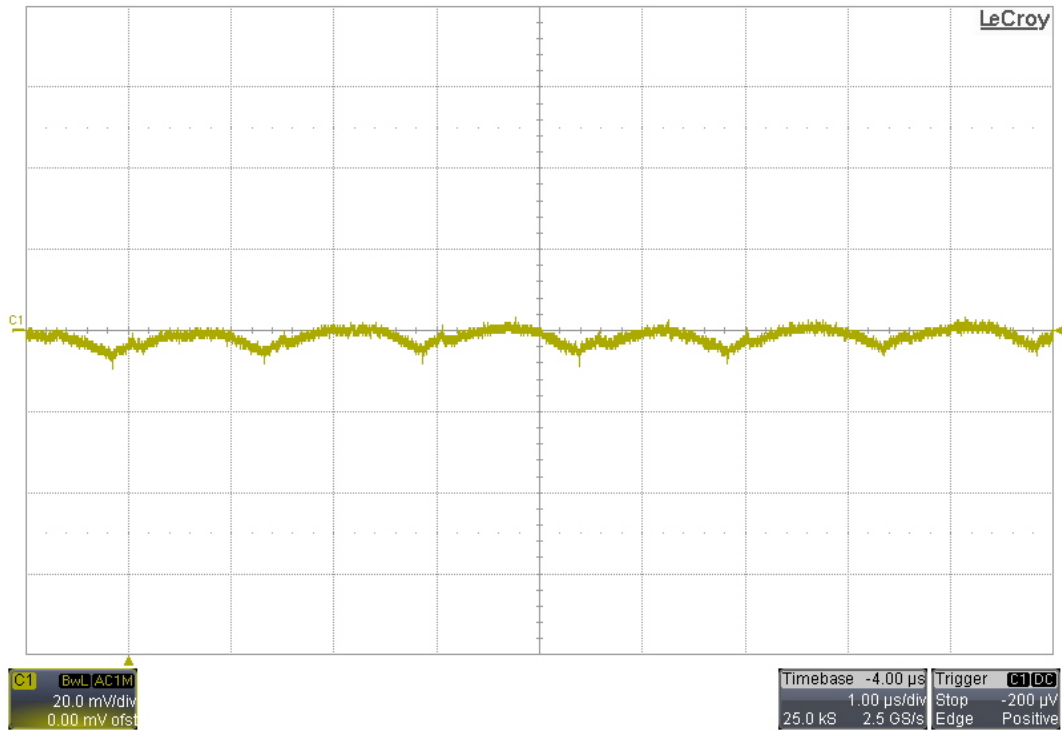
## 4 Startup – No Load



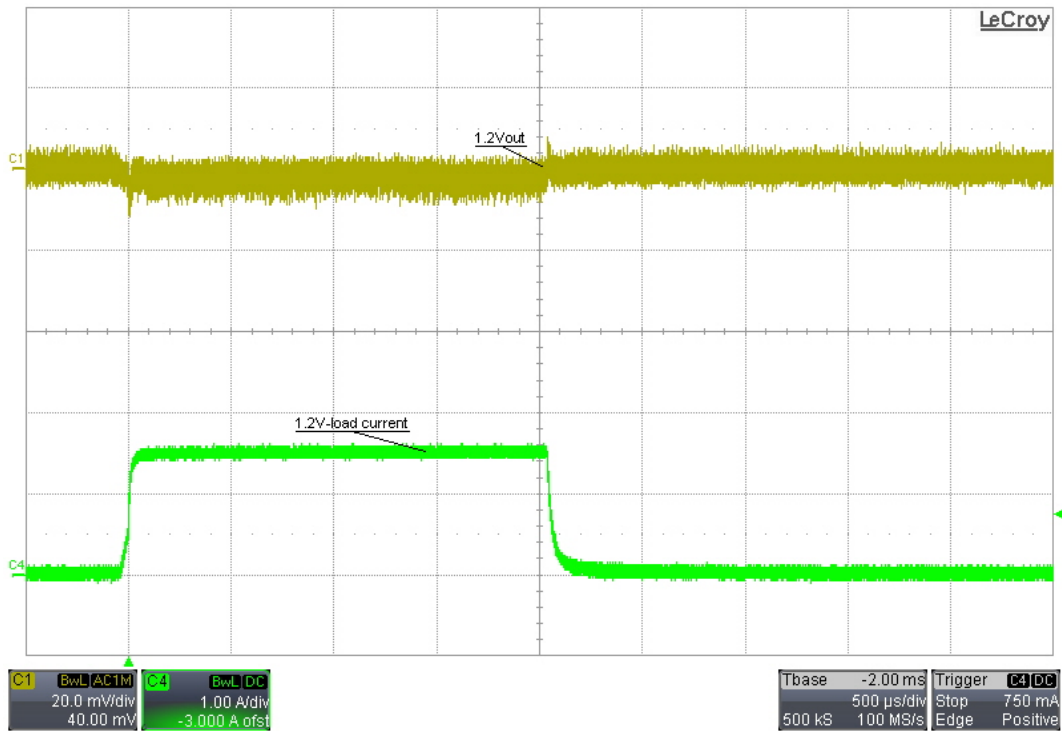
## 5 Startup – 1 $\Omega$ Load



## 6 Output Ripple Voltage

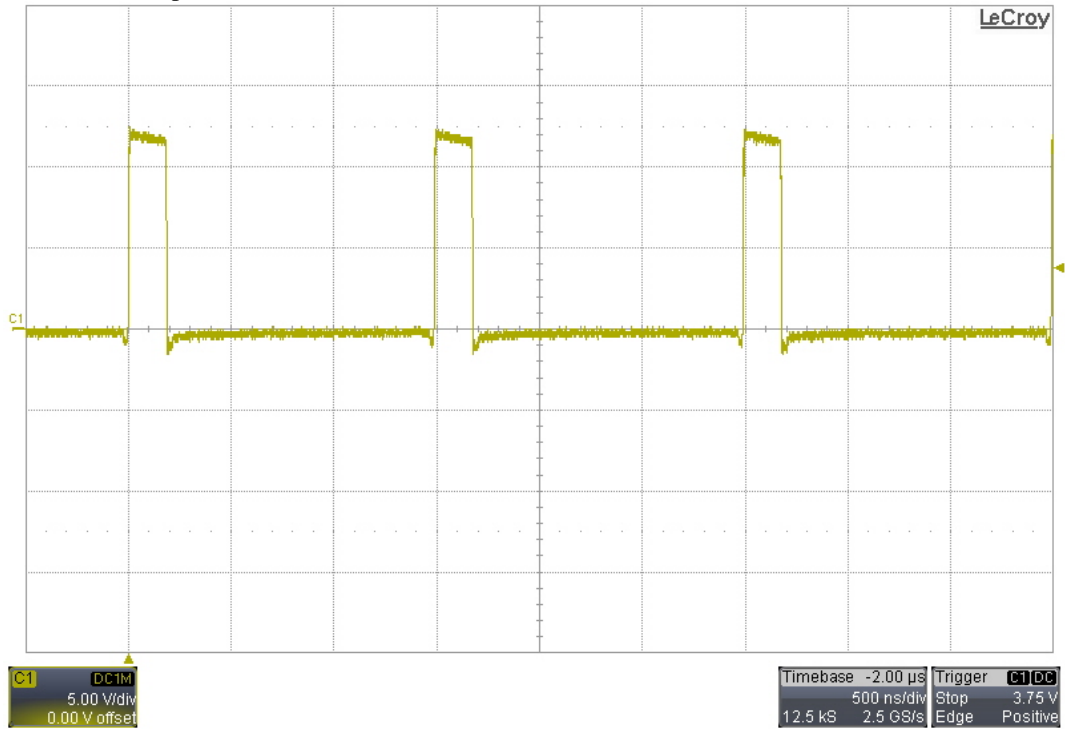


## 7 0A to 1.5A Transient



## 8 Switching Waveform

The image below shows the on pin 2 (SW) of U4.



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